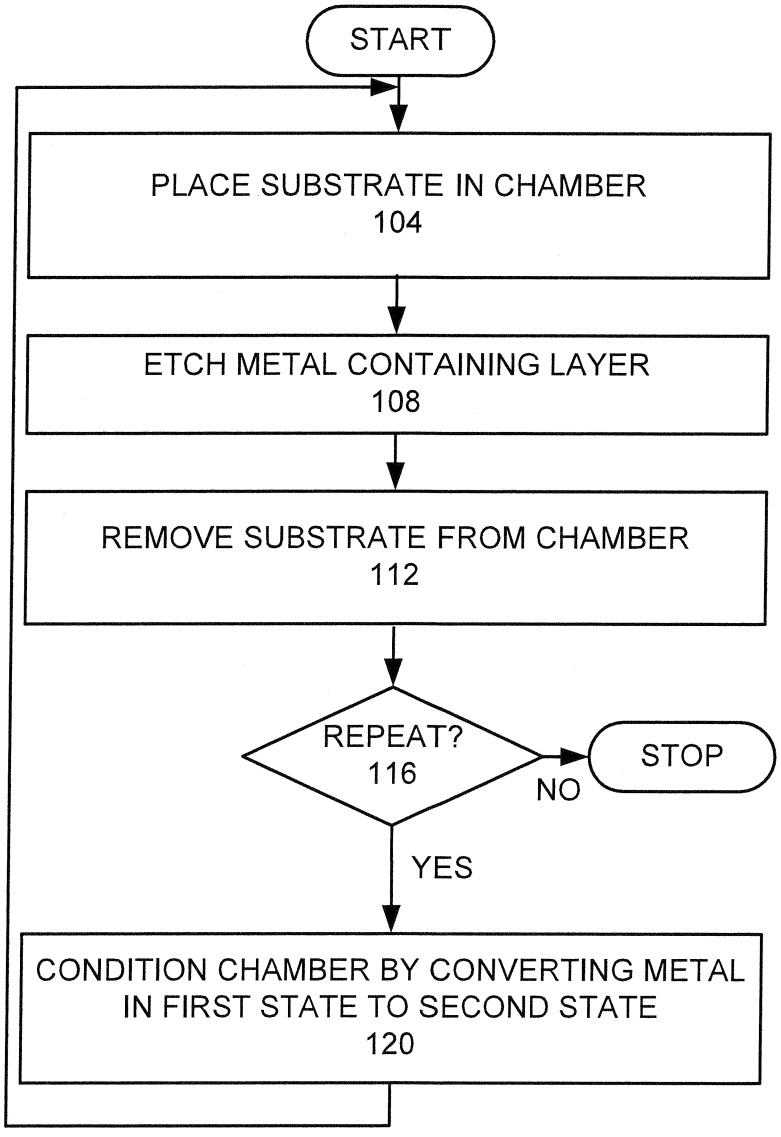

START
PLACE SUBSTRATE IN CHAMBER
104
ETCH METAL CONTAINING LAYER
108
REMOVE SUBSTRATE FROM CHAMBER
112
REPEAT?
116
NO
STOP
YES
CONDITION CHAMBER BY CONVERTING METAL IN FIRST STATE TO SECOND STATE
120

FIG. 1

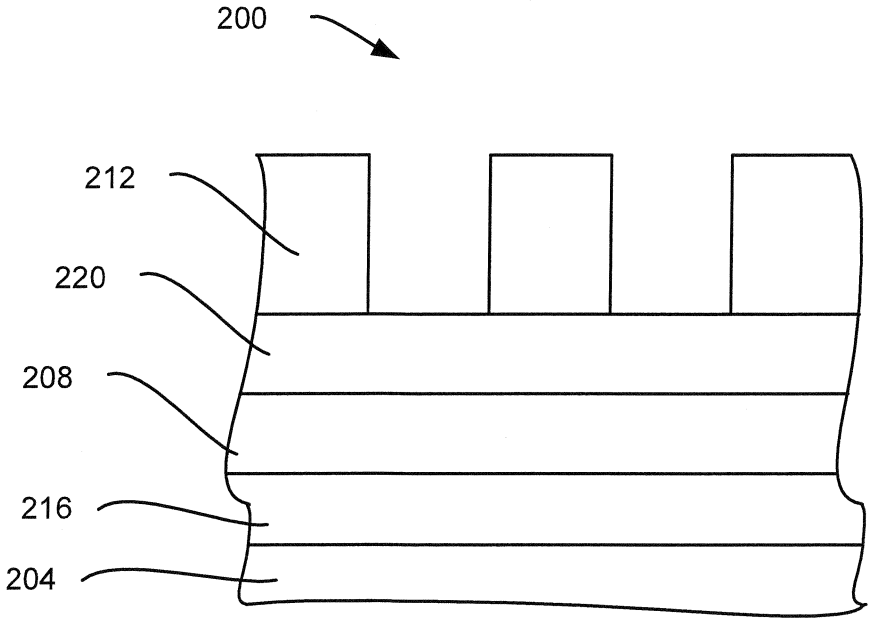


FIG. 2

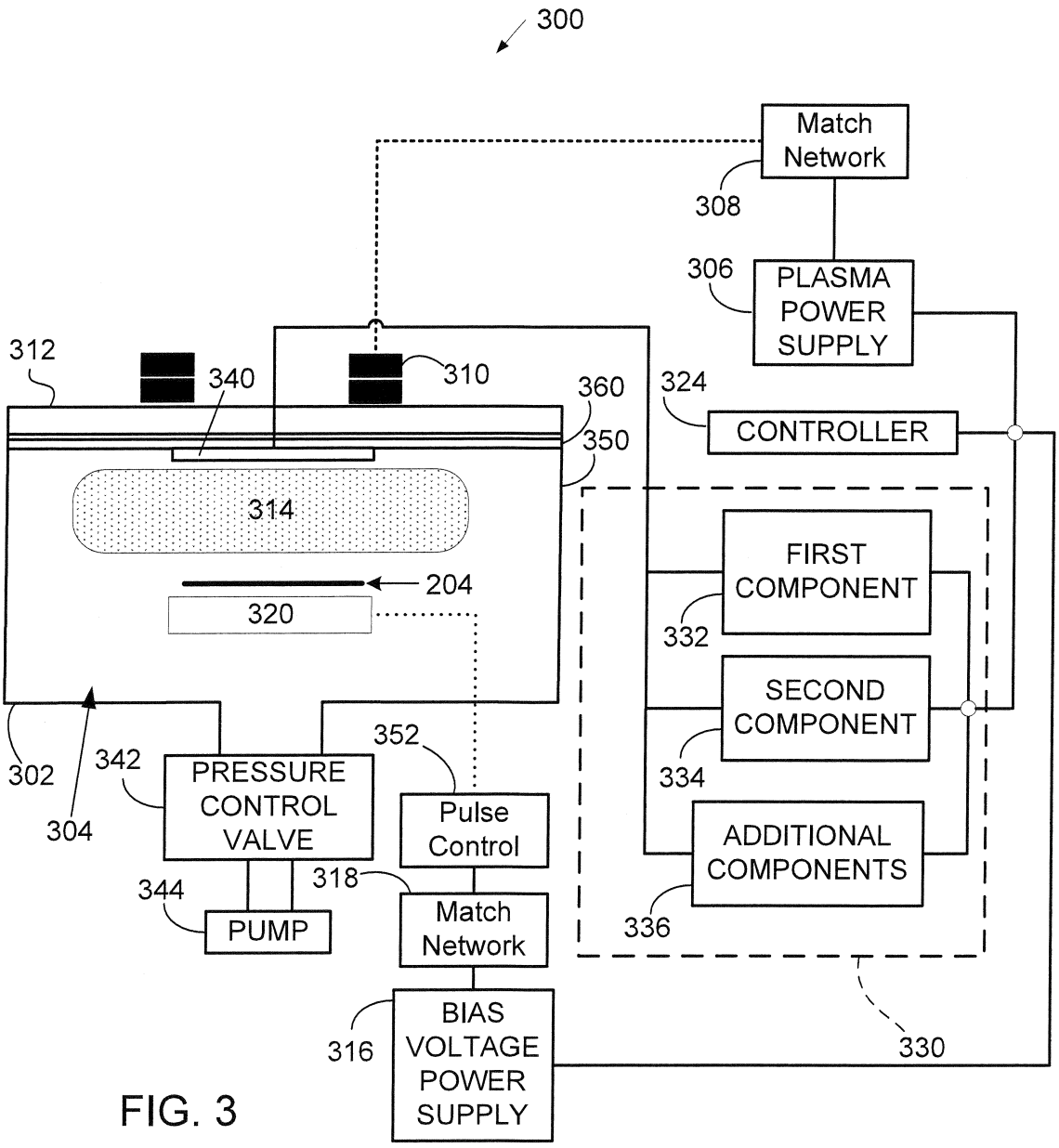

300
Match Network
308
306
PLASMA POWER SUPPLY
312
340
310
360
324
CONTROLLER
350
314
204
320
FIRST COMPONENT
332
SECOND COMPONENT
334
ADDITIONAL COMPONENTS
336
302
304
342
PRESSURE CONTROL VALVE
352
Pulse Control
318
344
PUMP
Match Network
316
BIAS VOLTAGE POWER SUPPLY
330

FIG. 3

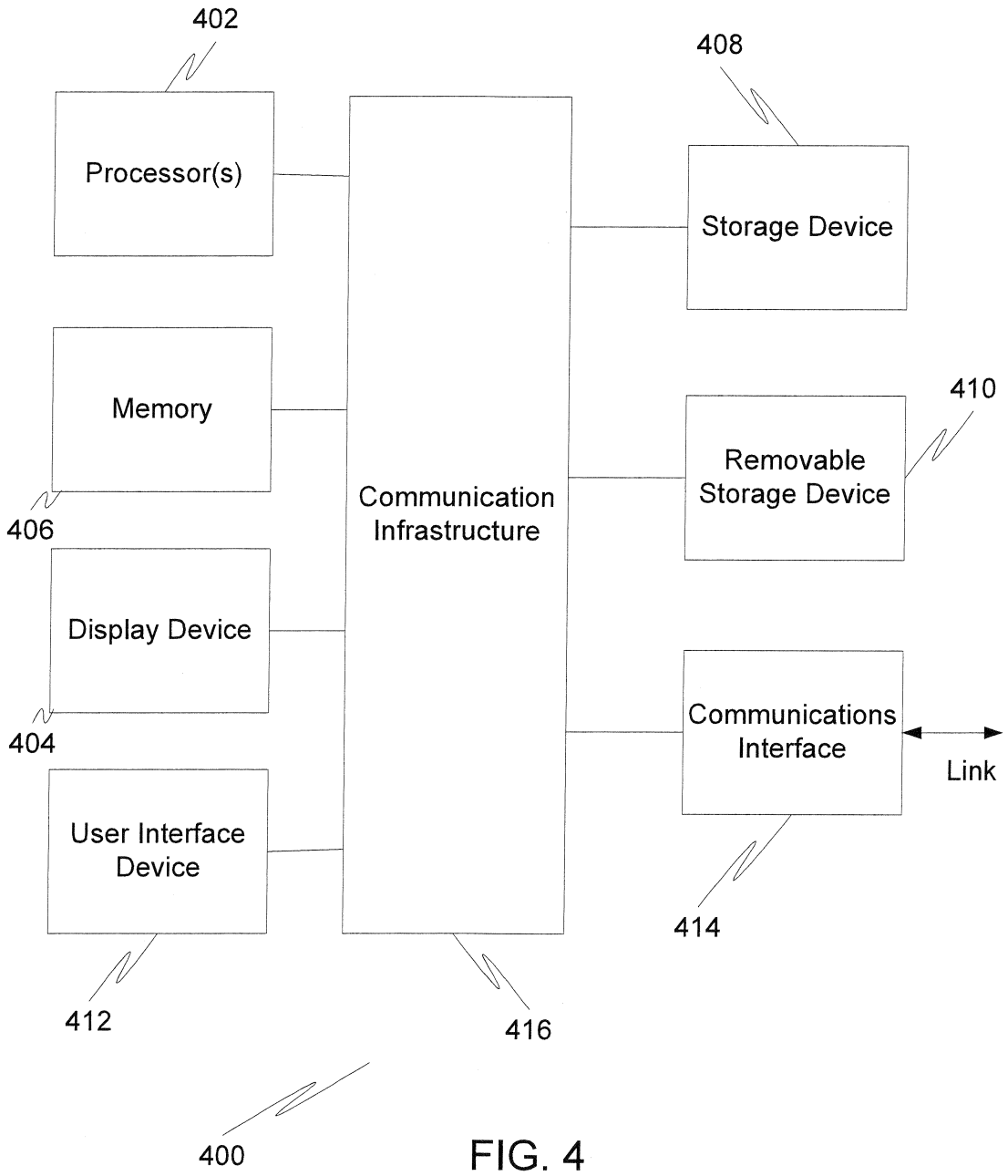

402
Processor(s)
408
Storage Device
Memory
406
Communication Infrastructure
410
Removable Storage Device
Display Device
404
Communications Interface
Link
User Interface Device
412
414
416
400

FIG. 4

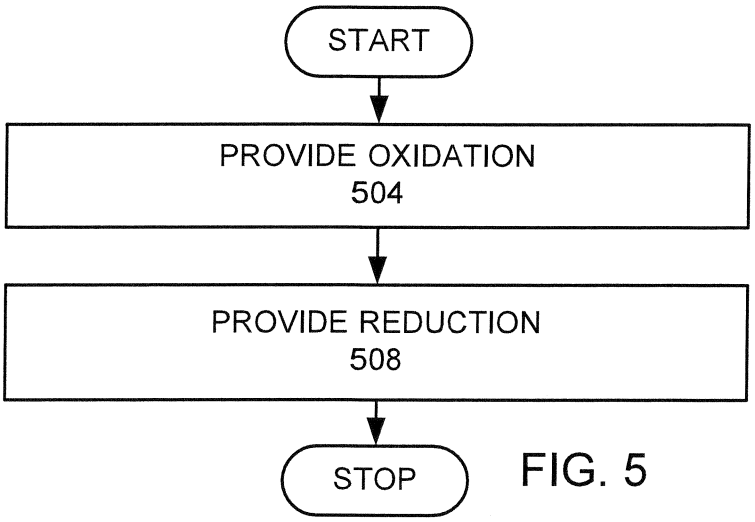


FIG. 5